

Title (en)

MATERIAL COMPRISING A STACK WITH A THIN ZINC-BASED OXIDE DIELECTRIC SUBLAYER AND METHOD FOR APPLYING SAID MATERIAL

Title (de)

MATERIAL MIT EINEM STAPEL MIT EINER DÜNNEN DIELEKTRISCHEN SCHICHT AUS ZINKBASIERTEM OXID UND VERFAHREN ZUR ANWENDUNG DES BESAGTEN MATERIALS

Title (fr)

MATERIAU COMPORTANT UN EMPILEMENT A SOUS-COUCHE DIELECTRIQUE FINE D'OXIDE A BASE DE ZINC ET PROCEDE DE DEPOT DE CE MATERIAU

Publication

EP 4172123 A1 20230503 (FR)

Application

EP 21740593 A 20210616

Priority

- FR 2006609 A 20200624
- FR 2021051082 W 20210616

Abstract (en)

[origin: WO2021260296A1] The invention relates to a material comprising a substrate (30) coated on one face (29) with a stack of thin layers (14) comprising at least one metallic functional layer (140) and comprising: - a zinc oxide, ZnO, based sublayer (129) between 0.3 and 5.0 nm thick; - a silicon-zirconium nitride, SixNyZrZ, based dielectric sublayer (127), underneath and in contact with the zinc oxide, ZnO, based sublayer (129), between 5.0 and 50.0 nm thick; - a silicon nitride Si3N4 based primary dielectric sublayer (125), underneath and in contact with the silicon-zirconium nitride, SixNyZrZ, based sublayer (127), between 5.0 and 30.0 nm thick; - and a titanium oxide, TiOx, based blocking layer (150) placed on and in contact with said functional layer (140).

IPC 8 full level

C03C 17/36 (2006.01)

CPC (source: EP)

C03C 17/36 (2013.01); **C03C 17/3618** (2013.01); **C03C 17/3626** (2013.01); **C03C 17/3642** (2013.01); **C03C 17/3644** (2013.01); **C03C 17/366** (2013.01); **C03C 2217/944** (2013.01)

Citation (search report)

See references of WO 2021260296A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

Designated validation state (EPC)

KH MA MD TN

DOCDB simple family (publication)

FR 3111890 A1 20211231; **FR 3111890 B1 20220701**; EP 4172123 A1 20230503; WO 2021260296 A1 20211230

DOCDB simple family (application)

FR 2006609 A 20200624; EP 21740593 A 20210616; FR 2021051082 W 20210616